

PFC THD Reduction and Efficiency Improvement by ZVS or Valley Switching

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High Performance Isolated

Abstract

When a PFC is in discontinuous conduction mode, the inductor current will resonant between the boost inductor and MOSFET parasite capacitance. The resonant current can be big enough to distort the PFC current significantly. This application note introduces a digital control scheme based on UCD3XXX to predict the position at which the resonant current first time rises back from negative to zero, and turning on the MOSFET at this position to minimize PFC current distortion. Since the switch node is either zero voltage or valley voltage at this position, the efficiency is also improved.

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Introduction

A PFC circuit, as shown in Figure1, with power level over 200W usually uses average-current mode control and operates at a constant switching frequency. The circuit's boost inductor current i_L can maintain continuous-conduction mode (CCM) for certain heavy load range. However, at light loads, the current becomes discontinuous. Once the boost inductor current declines to zero, the boost inductor, L, resonates with PFC MOSFET Q1's parasite capacitance C1.



Figure 1. Experimental digitally controlled 360W PFC circuit.

The resonant current can be big enough to distort the PFC current significantly, as shown in Figure 2a. Depending on the MOSFET's turn-on time, the resonant current contributes to average current in a different way in one switching cycle. In another word, the resonant current adds to the switching current in one switching cycle, but in next switching cycle, the current is subtracted from the switching current, which causes large current steps, as shown in zoom-in waveforms of Figure 2b. Since this effect occurs at much higher frequency than a PFC's current loop bandwidth at discontinuous-conduction mode (DCM), the current loop can not regulate the boost inductor current fast enough to compensate the abrupt current disturbance.



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Figure2. A typical current distortion waveform at light loads.

ZVS or valley switching control

A detailed investigation during the resonant is shown in Figure 3. In DCM mode, after i_L decrease to zero, the boost inductor, L, resonates with MOSFET capacitance C1. If the instantaneous a.c. voltage is lower than $\frac{1}{2}$ PFC output voltage, MOSFET's Vds can resonate to zero volts and be clamped by the MOSFET body diode. If the MOSFET can be turned on at the position that the current first time resonant back from negative to zero, the resonant current will not contribute to the switching current, the harmonic distortion caused by this resonation is eliminated.



Figure 3 Resonation between boost inductor and MOSFET output capacitance when Vin < 1/2Vout.

For PFC controlled by digital controller such as UCD3XXX, this position can be pre-calculated as follow: For steady state operation, a boost inductor's Volt-Second (V-S) is balance in each switching cycle. Given Q1 turn-on time TDa, the time for the boost inductor current i_L to return to zero is,

$$TDb = TDa^* Vin / (Vo-Vin)$$
(1)

During this resonation period when the boost inductor current i_L resonates back from negative value to zero at time tx, the V·S applied to the boost inductor maintains balanced as well. By using V·S balancing again, SA = SB + SC, Tx can be calculated as follow:

$$tx = \frac{1}{\omega r} * arcSin(\frac{Vin}{Vp}) + \frac{Vp}{Vin * \omega r} * \sqrt{1 - (\frac{Vin}{Vp})^2}$$
(2)

where Vp = (Vo-Vin) and ωr is the angular frequency of the resonant circuit ($\omega r = 1/2\pi Tr$). Equation (2) can be simplified to reduce processor computing time and an approximate tx value can be calculated by,

$$tx = Vo \cdot Tr / (8 \cdot Vin)$$
(3)

From equations (1) and (2) or (3),

$$Ts = TDa + TDb + Tr/4 + tx$$
(4)

Thus the position that the resonant current resonant back from negative to zero is predicted, UCD3XXX will reset its switching period so that the next PWM will turn at the position of tx. Since the Vds is zero at this point, a ZVS control is achieved.

If instantaneous a.c. input voltage Vin (=|Vac|) is higher than $\frac{1}{2}$ boost output voltage Vo, MOSFET Q1's Vds never resonates to zero volts, as shown in Figure 4. Instead, the boost inductor L will resonates freely with the MOSFET output capacitance C1.



Figure 4. Resonation between boost inductor and MOSFET output capacitance when Vin > 1/2Vout



In this case, tx is equals to Tr/4 and the predict switching period become,

$$Ts = TDa + TDb + Tr/4 + Tr/4$$
(5)

If the next PWM turns on at the position of tx, there is no ZVS as Vds is not zero, however, Vds is at its lowest point, this is called valley switching.

A simple hardware as shown in Figure 1 is used to implement this new control algorithm. Q1 is controlled by PFC's average mode current loop. Q2 is turned on at the same time of Q1 but turned off at the end of the predicted switching period Ts. A Synchronize signal is generated at the position tx to restart the next PWM pulse. The PFC is running with either ZVS or valley switching.

The above analysis assuming the MOSFET's output capacitance is constant. However, the MOSFET's output capacitance is actually non-linear vs. its drain to source voltage. The output capacitance of a typical MOSFET, such as SPP20N60C3, maintains relatively constant from 600V down to 50V, but the value increases by about 10 times at Vds=25V and nearly 100 times at Vds=0V. The nonlinearity introduces some error to the calculation when the instantaneous a.c. voltage is lower than $\frac{1}{2}$ PFC output voltage.

The waveforms are shown in Figure 5. When Vds valley voltage is lower than 50V, the nonlinear characteristic of the MOSFET output capacitance starts to affect Vds waveform, as shown in dash line in Figure 5. The actual valley occurs later than the calculated position. However, since the valley becomes flat, the switching loss increase caused by the premature turning-on of the MOSFET is insignificant.



Figure 5. Effect of nonlinear parasitic capacitance.

To ensure ZVS, instead of solely using Ts to update PWM switching period, a diode D2 connects to the switch node is proposed to provide a more reliable control. Q2 could be turned off too early due to calculation error, however, since Vds is still zero at this point, the Syn signal is blocked by D2 until the real tx is coming.

When load is increased and the boost inductor current is continuous, the calculated period Ts (=TDa + TDb + Tr/4 + tx) becomes always larger than the PWM switching period (= TDa + TDb). A new switching period starts before Q2 is turned off, therefore Q2 is on all the time and Syn remains low. For this case, the PFC returns to conventional hard-switching CCM operation disregarding input a.c. voltage.

Firmware implementation

A function called "handle_ZVS_control()" is created. All it does is calculated the Ts based on the equation above and generate a PWM pulse equals to Ts. This PWM pulse will turn on Q2 thus no Syn signal is generated during Ts. Once Ts expires, Q2 turns off, a Syn signal is generated to turn the next cycle MOSFET on at exactly the position of tx.

```
inline void handle_zvs_control(void) //calculate the ZVS/ZCS position, generate sync signal
         if(zvs_flag == 1) //this is a flag tells the ZVS control is enabled
                  iv.vbus_scaled = (iv.adc_avg[VBUS_CHANNEL] * VBUS_TO_VAC_SCALING) >> 15;
                  //scale vbus to match scale of vin Q12 * Q15 >> 15 = Q12
                  iv.cla output filtered = Filter1Regs.FILTERYNREAD.bit.YN + iv.cla output filtered -
                                         (iv.cla_output_filtered >> 2); //Q25
                  iv.numerator_1 = iv.vin_raw; //Vin, Q12
                  if(iv.vbus_scaled > iv.numerator_1)
                   {
                            iv.numerator_2 = iv.vbus_scaled - iv.numerator_1; //Vo-Vin, Q12
                   }
                  else
                   ł
                            iv.numerator_2 = 0;
                   }
                  if(iv.numerator_1 < (iv.vbus_scaled >> 1)) //if Vin < (Vout/2)
                   {
                            if(iv.numerator_1 < iv.min_vin)
                            {
                                     iv.numerator_1 = iv.min_vin; //vin is in denominator, clamp it
                            iv.numerator_3 = ((iv.cla_output_filtered >> 8) * (iv.switching_period >> 4)) >> 13;
                            //Ton, Q17*Q14>>13=Q18
                            iv.numerator_3 = (iv.numerator_3 * iv.vbus_scaled) >> 12; //Q18*Q12>>12=Q18
                            iv.numerator_3 = 8 * iv.numerator_1 * iv.numerator_3; //Q12*Q18=Q30
                            iv.numerator 4 = T_r * ((iv.vbus_scaled * iv.numerator 2) >> 12); //Q12*Q12>>12=Q12
                            iv.numerator_3 = iv.numerator_3 + iv.numerator_4; //numerator, Q30
                            iv.denominator = (8 * iv.numerator_1 * iv.numerator_2) >> 12; //Q12*Q12>>12=Q12
                            Dpwm3Regs.DPWMEV2.all = (iv.numerator_3 / iv.denominator) + (T_r >> 2);
                            //Q30/Q12=Q18, add 1/4 T_r
                   }
                  else
                   ł
                            iv.numerator_3 = ((iv.cla_output_filtered >> 8) * (iv.switching_period >> 4)) >> 13;
                            //Ton, Q17*Q14>>13=Q18
                            iv.numerator_3 = (iv.numerator_3 * iv.vbus_scaled) / iv.numerator_2;
                            //Ton+Toff, Q18*Q12/Q12 = Q18
```



}

}

```
Dpwm3Regs.DPWMEV2.all = iv.numerator_3 + (T_r >> 1); //Ton+Toff+1/2 T_r

}
Dpwm1Regs.DPWMSAMPTRIG1.all=Dpwm3Regs.DPWMEV2.all-(iv.sample_trigger_offset<<2);
//PWM frequency changed, update sample trigger accordingly
}
else
{
Dpwm1Regs.DPWMSAMPTRIG1.all = iv.switching_period - (iv.sample_trigger_offset * 4);
// sample at the end of period
}
```

At heavy load, the PFC enters CCM mode, there is no need to apply this control scheme any more. At high line, although this control scheme can achieve valley switching, the PWM frequency is also increased, the efficiency may or may not improved. The following function will automatically disable the control scheme at heavy load or high line.

```
inline void dynamic_system_optimization(void)
```

```
if(iv.vin_squared_average < 0x1400) //if vin < 160 volts
{
        if(iv.pis.output < 0x600) //enable ZVS control at light load
                 zvs_flag = 1; //enable ZVS control at light load
                 Dpwm1Regs.DPWMCTRL1.bit.EXT_SYNC_EN = 1; //sync to external
                 Dpwm3Regs.DPWMCTRL0.bit.MSYNC_SLAVE_EN = 0;
                 Dpwm3Regs.DPWMCTRL1.bit.EXT_SYNC_EN = 1; //sync to external
        -}
        else if(iv.pis.output > 0x650) //disable ZVS at heavy load
        {
                 zvs_flag = 0; //disable zvs control
                 Dpwm1Regs.DPWMCTRL1.bit.EXT_SYNC_EN = 0;
                 Dpwm3Regs.DPWMCTRL0.bit.MSYNC_SLAVE_EN = 1;
                 Dpwm3Regs.DPWMCTRL1.bit.EXT_SYNC_EN = 0;
        }
}
else //high line
{
        if(zvs_flag == 1) //disable ZVS at high line
        {
                 zvs_flag = 0; //disable zvs control
                 Dpwm1Regs.DPWMCTRL1.bit.EXT_SYNC_EN = 0;
                 Dpwm3Regs.DPWMCTRL0.bit.MSYNC_SLAVE_EN = 1;
                 Dpwm3Regs.DPWMCTRL1.bit.EXT_SYNC_EN = 0;
        }
}
```

ZVS and Valley Switching Experiment and Test Results

This predictive ZVS or valley switching control scheme is implemented in TI's PFC EVM PWR026 and PR977. The following results are gathered from PR977. Figure 5a shows input current waveforms at 120Vac input and 10% load with conventional fix frequency hard switching control. Figure 5b shows the

reduction of current harmonic after using this method. It can be seen that low frequency current distortion at the crossover points was almost completely eliminated. THD was reduced from 5.25% to 4.18% while efficiency was improved over 2%. Figure5c shows the PFC MOSFET achieves both ZVS and ZCS. At high line input and light loads, MOSFET Q1 can operate in either valley switching or ZVS/ZCS depending on the instantaneous a.c. voltage. Figure 6a and Figure 6b show current waveforms at 230V input and 20% load before and after this control is applied. The reduction of measured THD is not as significant as it appears. That is due to the 30th harmonic measurement limitation of the test equipment used. Figure 6c shows Vdc valley switching of Q1. Since the tx calculation equations are valid for both instantaneous a.c. voltages higher and lower than 1/2 Vo, no operating mode switching control is required. When the PFC operates at CCM, the computed period becomes larger than maximum PWM period, which is set based on hard-switching operation and no Syn pulse is generated. The circuit transitions between constant frequency mode and variable frequency one seamlessly. The PFC THD, Power Factor and efficiency data were collected and depicted in Figure 7 and Figure 8. Overall PFC efficiency was improved, except at high line and 10% load. The efficiency decrease at high line and 10% load was due to the additional switching loss caused by increased switching frequency. At these points, the increased switching loss surpasses the energy saved from valley switching. The digital controller knows its own switching frequency and it can calculate or measure output load to disable the valley switching control based on preset condition to avoid performance degrade and enable the control again to gain the efficient and THD benefit for the rest of operation conditions.







Figure 6. PFC current harmonic reduction and ZVS/ZCS operation at low line and 10% load . (a) With conventional control: THD= 5.25%, PF = 0.99 (b) With ZVS control: THD= 4.18%, PF=0.99 (c) waveforms with ZVS control







Figure 7. PFC current harmonic reduction and ZVS/ZCS operation at high line and 20% load.
(a) With conventional control: THD= 4.34%, PF = 0.96
(b) With valley switching control: THD= 4.18%, PF=0.97
(c) waveforms with valley switching control



(a)



(b)



(c)

Figure 8. THD, FP and efficiency comparison with and without ZVS or valley switching at low line





(a)



(c)

Figure 9. THD, FP and efficiency comparison with and without ZVS or valley switching at high line.

Conclusion

This predictive ZVS or valley switching control scheme can be implemented by TI's digital controller UCD3XXX. The position that the inductor current first time resonant from negative back to zero is calculated, and a simple hardware is used to generate a Syn signal at this point to restart the next PWM cycle. Since the switch node voltage is either zero or at its valley, a ZVS or valley switching is achieved. This control was proved to be valid for all line and load conditions and both CCM and DCM operations. It allows the PFC to transfer between constant frequency hard-switching mode and variable frequency ZVS or valley switching mode seamlessly without using any conditional mode switching mechanism. The control reduces current ripple significantly. It improves PFC overall performance, including THD, power factor and efficiency, at low line and light loads. Good PF improvement and some THD reduction were also achieved at high line. However, efficiency decrease was observed at below 10% load and at high line. This function can be enabled/disabled automatically by the controller based on input voltage and load condition.

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